Abstracts

Highly Integrated Three-Dimensional MMIC Single-Chip Receiver and Transmitter (1996 Vol. III [MWSYM])

I. Toyoda, T. Tokumitsu and M. Aikawa. "Highly Integrated Three-Dimensional MMIC Single-Chip Receiver and Transmitter (1996 Vol. III [MWSYM])." 1996 MTT-S International Microwave Symposium Digest 96.3 (1996 Vol. III [MWSYM]): 1209-1212.

A three-dimensional (3D) MMIC structure with thin polyimide-film layers on wafers significantly increases the integration level of MMICs. We newly developed 9. 2-12 GHz receiver and 9. 5-14 GHz transmitter chips with 20 dB gain using 3D MMIC technology. The integration levels of these chips are nearly three times as high as those of conventional planar ones.

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